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Name

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Signature

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application Of: Ciurzynski et al.

For: Wire Bonding Surface For Connecting An Electrical Energy
Storage Device To An Implantable Medical Device

the specification of which is being transmitted herewith

Assistant Commissioner of Patents
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT
Pursuant to 37 CFR 1.56**

1. Applicants submit herewith patents, publications or other information of which they are aware, which they believe may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR 1.56.

The filing of this Information Disclosure Statement (IDS) shall not be construed as a representation that a search has been made (37 CFR 1.56(g)), an admission that the information cited is, or is considered to be material to patentability or that no other material information exists.

The filing of this IDS shall not be construed as an admission against interest in any manner (Notice of Jan. 9, 1992, 1135 O.G. 13-25, at 25).

2. Attached is Form PTO-1449. Legible copies of all items listed accompany this IDS.

IDS For: Wire Bonding Surface For Connecting An Electrical
Energy Storage Device To An Implantable Medical
Device
Inventor: Ciurzynski et al.

3. A concise explanation of the possible relevance of the listed information items is as follows:

Patents:

U.S. Patent No. 4,371,231 to Jung is directed to an electrically conductive connection consisting of a very thin gold wire 3 and a metal contact dot 1 situated on an electrical component or on an integrated circuit. The contact dot includes a plurality of rectangular perforation holes 4 contacted by the nailhead 2 of the gold wire 3. The other end of the gold wire connects to an external terminal which is not further described.

U.S. Patent No. 3,418,422 to Bradham III teaches an attachment for integrated circuit leads comprising a Kovar lead 7 electrolessly plated with nickel. Gold is electrolessly plated over the nickel. The electroless gold and the electroless nickel form a solid solution type of alloy which normally has a minimum melting point of 950°C. However, since the electroless nickel melts at 890°C due to the presence of phosphorous, the gold will be dissolved at this temperature or below. Thus, the bond is readily formed in a temperature range of about 850° to 900°C, which is sufficiently below the melting point of copper at 1,083°C.

U.S. Patent No. 2,568,242 to Matteson, Jr. describes an electrical contact having a circular and relatively thin head 1 comprising two layers 3 and 4 of a suitable electrical contact material and a base material, respectively. For example, the electrical contact layer 3 may be gold, silver, platinum, while

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the base layer 4 may be bronze or copper. The bonding head is also described as having other shapes such as square and oval.

U.S. Patent No. 5,116,700 to Takeda describes a power source element 10 having connecting terminals 8 which are affixed to a circuit board 12 through a solder bonding portion 11. Each connecting terminal has a top end portion having a relatively large solder plate 9 to increase the bonding strength to the circuit board. The connecting terminal piece 8 has a reinforcement structure such that a base portion 20 is arranged perpendicular to the solder plate 9 to sufficiently support the weight of the power source 10.

4. The remaining patents on the attached Form PTO 1449 were located during a patentability search or were cited in the prosecution of the parent application Serial No. 09/939,351.

5. The person making this statement is the agent who signs below, who makes this statement on the information supplied by the inventors and the information in the agent's file.

Respectfully submitted,

By:



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PTO/SB/08A(08/00)

Approved for use through 10/31/2002, OMB 0651-0031

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT***(Use as many sheets as necessary)*

INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>				Application Number		
				Filing Date		August 27, 2003
				First Named Inventor		Ciurzynski et al.
				Group Art Unit		
				Examiner Name		
Sheet	4	of	4	Attorney Docket Number		37505.0243

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. 1	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code 2 (if known)			
	1	4,371,231		Jung	02-01-1983	
	2	3,418,422		A. C. Bradham III	12-24-1968	
	3	2,568,242		G. A. Matteson, Jr.	09-18-1951	
	4	5,116,700		Takeda	05-26-1992	
	5	5,693,170		Li	12-02-1997	
	6	4,196,960		Gelfand	04-08-1980	
	7	4,168,876		Balde	09-25-1979	
	8	4,151,544		Riff	04-24-1979	
	9	3,826,000		Du Rocher et al.	07-30-1974	
	10	3,519,977		D. D. Swearingen	07-07-1970	
	11	2,715,169		V. L. High	08-09-1955	
	12	2,700,087		J. H. Stevens	01-18-1955	
	13	2,575,965		A. F. Rock	11-20-1951	
	14	2,434,992		G. Durst	01-27-1948	
	15	2,246,931		E. Chiffey	06-24-1941	
	16	542,953		F.A. & N. Von Alimonda	07-16-1985	
	17	5,072,730		Lee	12-07-1991	
	18	5,522,861		Sikorski et al.	06-04-1996	
	19	5,877,472		Campbell et al.	03-02-1999	

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. 1	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear	T6
		Office3	Number4	Kind Code5 (if known)				

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

1 Unique citation designation number. 2 See attached Kinds of U.S. Patent Documents. 3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. 6 Applicant is to place a check mark here if English language Translation is attached.